



**SLOVENSKI STANDARD
SIST EN IEC 63287-2:2023**

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**Polprevodniški elementi - Smernice za načrtovanje ocenjevanja zanesljivosti - 2.
del: Koncept profila namembnosti (IEC 63287-2:2023)**

Semiconductor devices - Guidelines for reliability qualification plans - Part 2: Concept of mission profile (IEC 63287-2:2023)

Halbleiterbauelemente - Richtlinien für Zuverlässigkeitsqualifizierungspläne - Teil 2:
Konzept des Einsatzprofils (IEC 63287-2:2023)

Dispositifs à semiconducteurs - Lignes directrices concernant les plans de qualification de la fiabilité - Partie 2: Concept de profil de mission (IEC 63287-2:2023)

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SIST EN IEC 63287-2:2023

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EUROPEAN STANDARD

EN IEC 63287-2

NORME EUROPÉENNE

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May 2023

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Semiconductor devices - Guidelines for reliability qualification plans - Part 2: Concept of mission profile (IEC 63287-2:2023)

Dispositifs à semiconducteurs - Lignes directrices
concernant les plans de qualification de la fiabilité - Partie 2:
Concept de profil de mission
(IEC 63287-2:2023)

Halbleiterbauelemente - Richtlinien für
Zuverlässigkeitsqualifizierungspläne - Teil 2: Konzept des
Einsatzprofils
(IEC 63287-2:2023)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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EN IEC 63287-2:2023 (E)**European foreword**

The text of document 47/2796/FDIS, future edition 1 of IEC 63287-2, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 63287-2:2023.

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- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2026-05-03

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In the official version, for Bibliography, the following notes have to be added for the standard indicated:

IEC 60068-2-1 NOTE Approved as EN 60068-2-1

IEC 60068-2-30 NOTE Approved as EN 60068-2-30

IEC 60749-11 NOTE Approved as EN 60749-11

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

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NORME INTERNATIONALE



**Semiconductor devices – Guidelines for reliability qualification plans –
Part 2: Concept of mission profile**

**Dispositifs à semiconducteurs – Lignes directrices concernant les plans de
qualification de la fiabilité –**
Partie 2: Concept de profil de mission

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CONTENTS

FOREWORD	3
1 Scope	5
2 Normative references	5
3 Terms and definitions	5
4 Mission profile	5
4.1 Concept of mission profile	5
4.2 Example of reliability test plan considering the mission profile of automotive engine peripherals application (1)	6
4.3 Example of reliability test plan considering the mission profile of automotive engine peripherals application (2)	8
4.4 Example of reliability test plan considering the mission profile of automotive cabin peripherals application	9
5 Calculation examples of mission profiles (Calculation of sample and test time of life tests)	10
Bibliography	15
Figure 1 – Example of mission profile for automotive application	6
Table 1 – Trial calculation example of equivalent time under operating life test based on consideration of the mission profile (automotive application in the engine peripheral)	7
Table 2 – Trial calculation example of number of samples/test time of operating life test with consideration of the mission profile (Automotive application in the engine peripheral)	7
Table 3 – Trial calculation example of equivalent time under operating life test with consideration of the mission profile (automotive application in the engine peripheral)	8
Table 4 – Trial calculation example of equivalent time under operating life test with consideration of the mission profile (Automotive application in the engine peripheral)	9
Table 5 – Trial calculation example of equivalent time under operating life test with consideration of the mission profile (automotive application in the cabin peripheral)	9
Table 6 – Trial calculation example of number of samples/test time of high temperature operating life test with consideration of the mission profile (Automotive application in the cabin peripheral)	10
Table 7 – Calculation examples of mission profiles (Calculation of sample and test time of life tests)	11
Table 8 – Calculation examples of mission profiles (Calculation of sample and test time of life tests)	13

INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**SEMICONDUCTOR DEVICES –
GUIDELINES FOR RELIABILITY QUALIFICATION PLANS –**
Part 2: Concept of mission profile**FOREWORD**

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IEC 63287 Part 2 has been prepared by IEC technical committee 47: Semiconductor devices. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47/2796/FDIS	47/2803/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

This International Standard is to be read in conjunction with IEC 63287-1.

A list of all parts in the IEC 63287 series, published under the general title *Semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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SEMICONDUCTOR DEVICES – GUIDELINES FOR RELIABILITY QUALIFICATION PLANS –

Part 2: Concept of mission profile

1 Scope

This part of IEC 63287 gives guidelines for the development of reliability qualification plans using the concept of mission profile, based on the environmental conditioning and proposed usage of the product. This document is not intended for military- and space-related applications.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 63287-1:2021, *Semiconductor devices – Generic semiconductor qualification guidelines – Part 1: Guidelines for IC reliability qualification*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

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ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <https://www.electropedia.org/>
- ISO Online browsing platform: available at <https://www.iso.org/obp>

3.1

failure mode

style classification of a fault phenomenon which causes product failure

Note 1 to entry: Disconnection, a short circuit, occasional loss, abrasion, characteristic deterioration, etc. are typical items considered as failure modes.

4 Mission profile

4.1 Concept of mission profile

In designing the reliability test plan, the test plan greatly changes depending on how the environmental conditions of the LSI is assumed. For example, in the case of electronic units for automotive application installed in the vicinity of the engine, operational temperature gradually rises by the heat generated by the engine but the temperature decreases after the engine stops, meaning that the unit is not always subjected to severe temperature conditions. The set of changing environmental temperature conditions and their time ratio is called the “mission profile”. Because mission profile depends on multiple factors such as operational duty of LSI, installation environment, generation of heat by peripheral parts, etc., it cannot be unconditionally standardized. Therefore, it is important to agree the mission profile between the LSI vendor and the user and decide on accurate test conditions.